

# Underfill Material - Global Market Outlook (2017-2026)

<https://marketpublishers.com/r/UB425FEF0C5EN.html>

Date: June 2019

Pages: 168

Price: US\$ 4,150.00 (Single User License)

ID: UB425FEF0C5EN

## Abstracts

According to Statistics MRC, the Global Underfill Material Market is accounted for \$240.56 million in 2017 and is expected to reach \$535.56 million by 2026 growing at a CAGR of 9.3% during the forecast period. Rising demand in automotive and military industries is the major key factors driving the market growth. Moreover, flip chip packaging of low-k devices is providing opportunities for the market growth. However, reducing profit margins of underfill suppliers may restrain the market growth.

Underfill materials are fused formulations of inorganic fillers and organic polymers which can be used as a semiconductor packaging to attain better quality of thermo-mechanical presentation. Molded underfill (MUF), Capillary underfill (CUF) and no flow underfill (NUF) are some techniques which are used in underfill materials.

By Product, Capillary Underfill Material (CUF) held considerable growth during forecast period due recent developments in the electronic industry. It is used in several packaging techniques which include ball grid array, chip scale packaging, flip chip, and others. By geography, Asia Pacific commanded considerable market share attributed to high adoption of these underfill materials in various industries in China.

Some of the key players profiled in the Underfill materials include H.B Fuller, Zymet, Yincac, Advanced Material, Nordson Corporation, Henkel, Master Bond, Epoxy Technology, NAMICS Corporation and Finetech.

Products Covered:

No Flow Underfill Material (NUF)

Capillary Underfill Material (CUF)

## Molded Underfill Material (MUF)

### Applications Covered:

Chip Scale Packaging (CSP)

Ball Grid Array (BGA)

Flip Chips

### Regions Covered:

North America

US

Canada

Mexico

Europe

Germany

UK

Italy

France

Spain

Rest of Europe

Asia Pacific

Japan

China

India

Australia

New Zealand

South Korea

Rest of Asia Pacific

South America

Argentina

Brazil

Chile

Rest of South America

Middle East & Africa

Saudi Arabia

UAE

Qatar

South Africa

Rest of Middle East & Africa

What our report offers:

Market share assessments for the regional and country level segments

Market share analysis of the top industry players

Strategic recommendations for the new entrants

Market forecasts for a minimum of 9 years of all the mentioned segments, sub segments and the regional markets

Market Trends (Drivers, Constraints, Opportunities, Threats, Challenges, Investment Opportunities, and recommendations)

Strategic recommendations in key business segments based on the market estimations

Competitive landscaping mapping the key common trends

Company profiling with detailed strategies, financials, and recent developments

Supply chain trends mapping the latest technological advancements

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